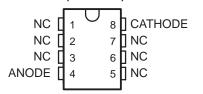
LM285-2.5, LM385-2.5, LM385B-2.5 MICROPOWER VOLTAGE REFERENCES

SLVS023J - JANUARY 1989 - REVISED MARCH 2005

- Operating Current Range . . . 20 μA to 20 mA
- 1.5% and 3% Initial Voltage Tolerance
- Reference Impedance
 - LM385 . . . 1 Ω Max at 25°C
 - All Devices . . . 1.5 Ω Max Over Full Temperature Range
- Very Low Power Consumption
- Applications
 - Portable Meter References
 - Portable Test Instruments
 - Battery-Operated Systems
 - Current-Loop Instrumentation
 - Panel Meters
- Interchangeable With Industry-Standard LM285-2.5 and LM385-2.5

LM285-2.5 . . . D PACKAGE LM385-2.5, LM385B-2.5 . . . D OR PW PACKAGE (TOP VIEW)



NC - No internal connection

LM285-2.5, LM385-2.5, LM385B-2.5... LP PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These micropower two-terminal band-gap voltage references operate over a 20-µA to 20-mA current range and feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming provides tight voltage tolerance. The band-gap reference for these devices has low noise and long-term stability.

ORDERING INFORMATION

TA	V _Z TOLERANCE	PACKAG	BE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		COIC (D)	Tube of 75	LM385D-2-5	205.05	
		SOIC (D)	Reel of 2000	LM385DR-2-5	385-25	
	20/	TO226/TO 02 (LD)	Tube of 1000	LM385LP-2-5	205 25	
	3%	TO226/TO-92 (LP)	Reel of 2000	LM385LPR-2-5	385-25	
		TOCOD (DIA)	Tube of 150	LM385PW-2-5	205.05	
000 to 7000		TSSOP (PW)	Reel of 2000	LM385PWR-2-5	385-25	
0°C to 70°C	4.50/	COIC (D)	Tube of 75	LM385BD-2-5	205025	
		SOIC (D)	Reel of 2000	LM385BDR-2-5	385B25	
		T0000/T0 00 // D)	Tube of 1000	LM385BLP-2-5	385-25	
	1.5%	TO226/TO-92 (LP)	Reel of 2000	LM385BLPR-2-5	365-25	
		TOCOD (DIA)	Tube of 150	LM385BPW-2-5	205025	
		TSSOP (PW)	Reel of 2000	LM385BPWR-2-5	385B25	
		SOIC (D)	Tube of 75	LM285D-2-5	205 25	
4000 1- 0500	4 50/	SOIC (D)	Reel of 2000	LM285DR-2-5	285-25	
–40°C to 85°C	1.5%	TO226/TO-92 (LP)	Tube of 1000	LM285LP-2-5	285-25	
		10220/10-92 (LP)	Reel of 2000	LM285LPR-2-5	285-25	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SLVS023J - JANUARY 1989 - REVISED MARCH 2005

description/ordering information (continued)

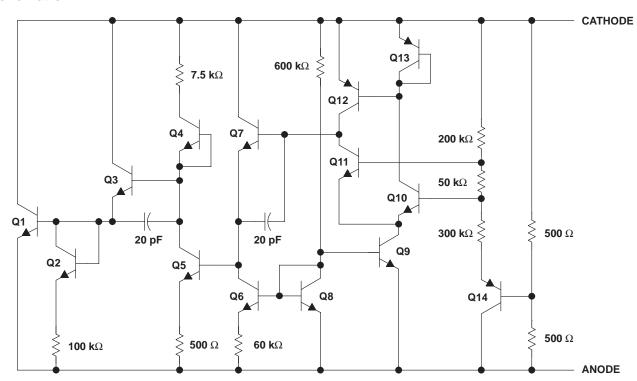
The design makes these devices exceptionally tolerant of capacitive loading and, thus, easier to use in most reference applications. The wide dynamic operating temperature range accommodates varying current supplies, with excellent regulation.

The extremely low power drain of this series makes them useful for micropower circuitry. These voltage references can be used to make portable meters, regulators, or general-purpose analog circuitry, with battery life approaching shelf life. The wide operating current range allows them to replace older references with tighter-tolerance parts.

symbol



schematic



NOTE A: All component values shown are nominal.

SLVS023J - JANUARY 1989 - REVISED MARCH 2005

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Reverse current, I _R		30 mA
Forward current, I _F		10 mA
Package thermal impedance, θ_{JA} (see Notes 1 and 2):	D package	97°C/W
	LP package	140°C/W
	PW package	149°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10	seconds	260°C
Storage temperature range, T _{stq}		-65°C to 150°C

recommended operating conditions

			MIN	MAX	UNIT
ΙZ	Reference current		0.02	20	mA
т.	Operating free cir temperature renge	LM285-2.5	-40	85	Ç
IA	Operating free-air temperature range	LM385-2.5, LM385B-2.5	0	70	

electrical characteristics at specified free-air temperature

		TEST		LI	/1285-2.	5	LI	M385-2.	5	LM	385B-2	.5	
PAF	RAMETER	CONDITIONS	T _A ‡	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
٧z	Reference voltage	I _Z = 20 μA to 20 mA	25°C	2.462	2.5	2.538	2.425	2.5	2.575	2.462	2.5	2.538	V
αγΖ	Average temperature coefficient of reference voltage§	I _Z = 20 μA to 20 mA	Full range		±20			±20			±20		ppm/°C
	Change in	I _Z = 20 μA	25°C			1			2			2	
	reference voltage with	to 1 mA	Full range			1.5			2			2	\/
ΔV_{Z}		•	•	•	$I_Z = 1 \text{ mA}$	25°C	10	20				20	
	current	to 20 mA	Full range			30			30			30	
$\Delta V_{Z}/\Delta t$	Long-term change in reference voltage	I _Z = 100 μA	25°C		±20			±20			±20		ppm/khr
I _{Z(min)}	Minimum reference current		Full range		8	20		8	20		8	20	μА
_	Reference	1 100 1	25°C		0.2	0.6		0.4	1		0.4	1	
ZZ	impedance	I _Z = 100 μA	Full range			1.5			1.5			1.5	Ω
V _n	Broadband noise voltage	I _Z = 100 μA, f = 10 Hz to 10 kHz	25°C		120			120			120		μV

[‡] Full range is 0°C to 70°C for the LM385-2.5 and LM385B-2.5, and -40°C to 85°C for the LM285-2.5.

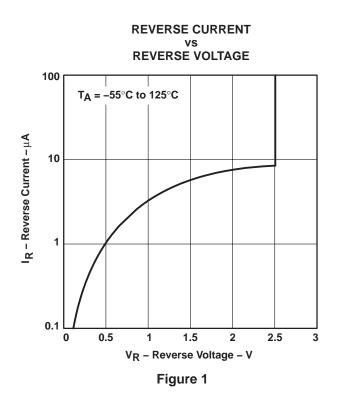
[§] The average temperature coefficient of reference voltage is defined as the total change in reference voltage divided by the specified temperature

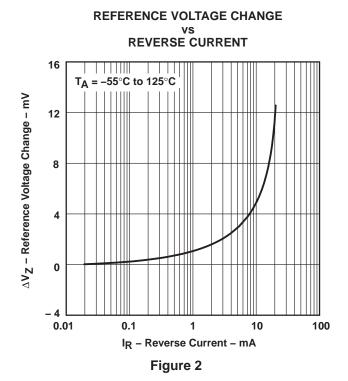


[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

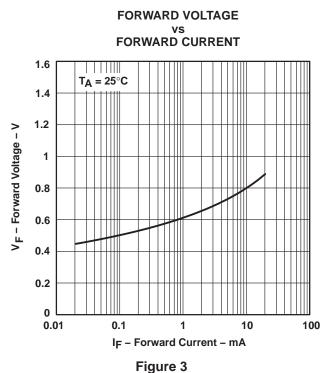
NOTES: 1. Maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$. Operation at the absolute maximum T_J of 150°C can affect reliability. 2. The package thermal impedance is calculated in accordance with JESD 51-7.

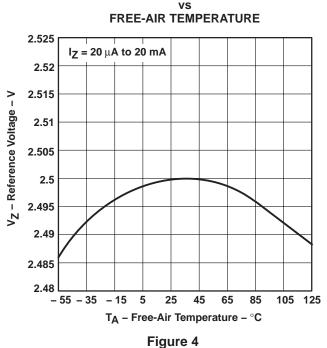
TYPICAL CHARACTERISTICS[†]





REFERENCE VOLTAGE

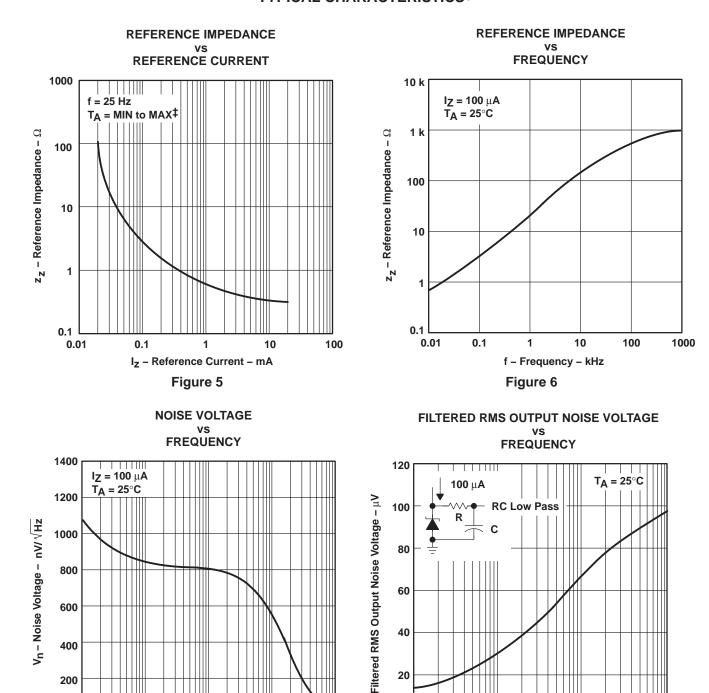




[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS[†]



100 k

10 k

10

100

1 k

f - Frequency - Hz

Figure 7



0

0.1

f - Frequency - kHz

Figure 8

100

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

TYPICAL CHARACTERISTICS[†]

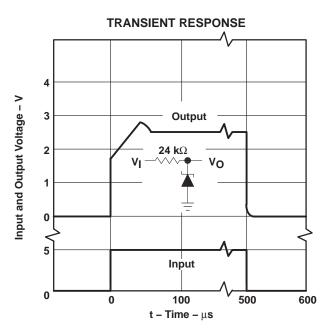
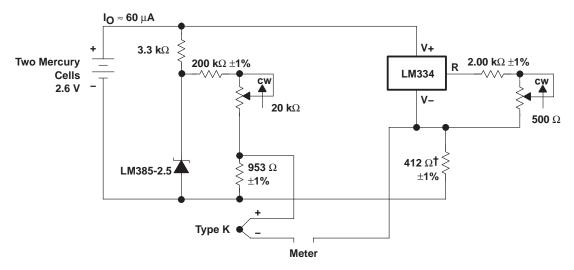


Figure 9

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



APPLICATION INFORMATION



 † Adjust for 12.17 mV at 25°C across 412 Ω

Figure 10. Thermocouple Cold-Junction Compensator

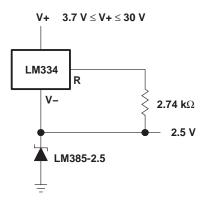


Figure 11. Operation Over a Wide Supply Range

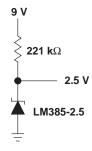


Figure 12. Reference From a 9-V Battery

28-Aug-2010

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
LM285D-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM285DE4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM285DG4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM285DR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
LM285DRE4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
LM285DRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribute or Sales Office
LM285LP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distribut or Sales Office
LM285LPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distribut or Sales Office
LM285LPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM285LPRE3-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM385BD-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
LM385BDE4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
LM385BDG4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distribut or Sales Office
LM385BDR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385BDRE4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385BDRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385BLP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distribut or Sales Office
LM385BLPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distribut or Sales Office





28-Aug-2010 www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
LM385BLPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM385BLPRE3-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM385BPWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385BPWRE4-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385BPWRG4-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385D-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385DE4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385DG4-2-5	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385DR-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385DRE4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385DRG4-2-5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
LM385LP-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distributor or Sales Office
LM385LPE3-2-5	ACTIVE	TO-92	LP	3	1000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Contact TI Distributor or Sales Office
LM385LPR-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM385LPRE3-2-5	ACTIVE	TO-92	LP	3	2000	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	Purchase Samples
LM385PWR-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385PWRE4-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
LM385PWRG4-2-5	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.



PACKAGE OPTION ADDENDUM

28-Aug-2010

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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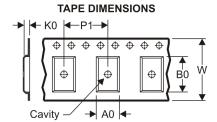




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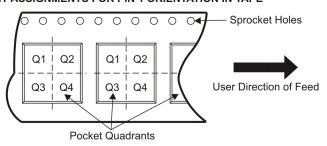
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

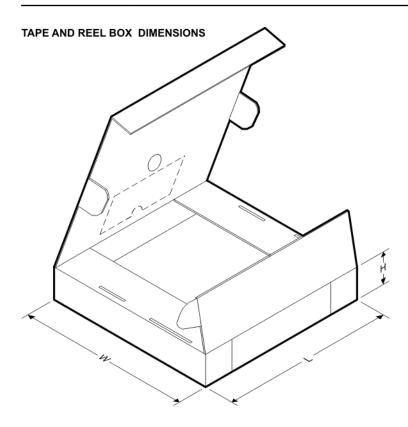
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385BDR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385BPWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM385DR-2-5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM385PWR-2-5	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1





*All dimensions are nominal

All difficultions are norminal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285DR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385BDR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385BPWR-2-5	TSSOP	PW	8	2000	346.0	346.0	29.0
LM385DR-2-5	SOIC	D	8	2500	340.5	338.1	20.6
LM385PWR-2-5	TSSOP	PW	8	2000	346.0	346.0	29.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



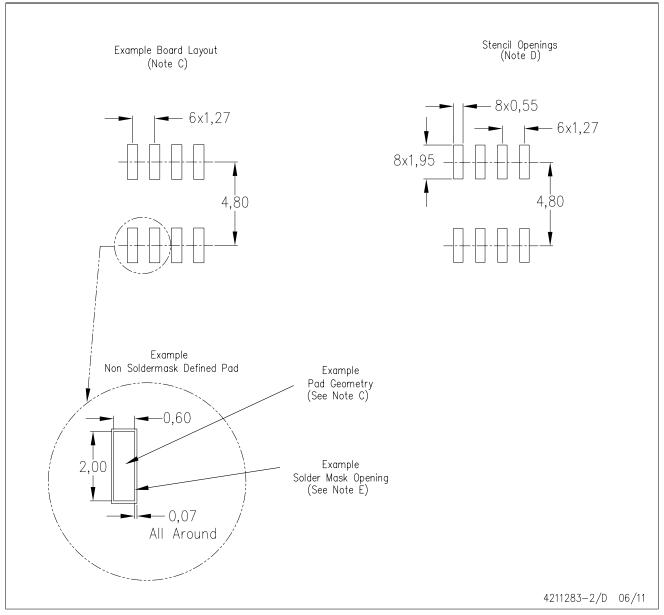
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



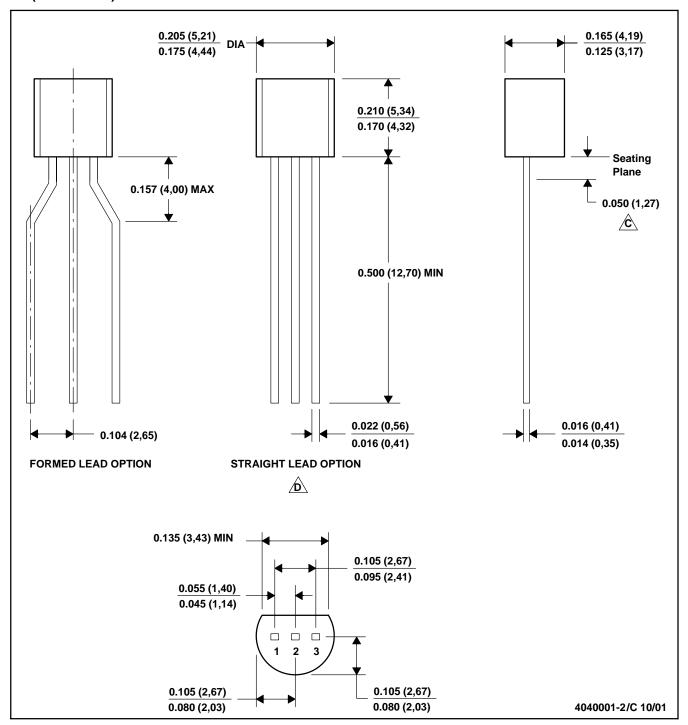
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice. $\hfill \hfill \$

C.\ Lead dimensions are not controlled within this area

D. FAlls within JEDEC TO -226 Variation AA (TO-226 replaces TO-92)

E. Shipping Method:

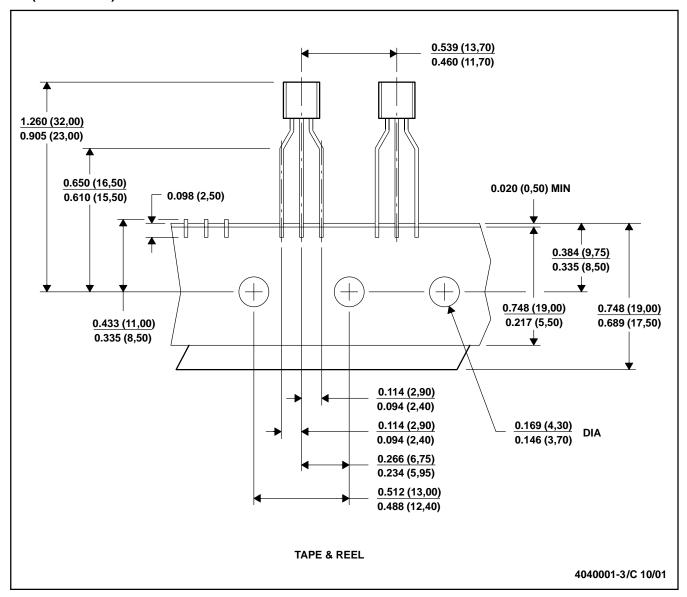
Straight lead option available in bulk pack only.

Formed lead option available in tape & reel or ammo pack.



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



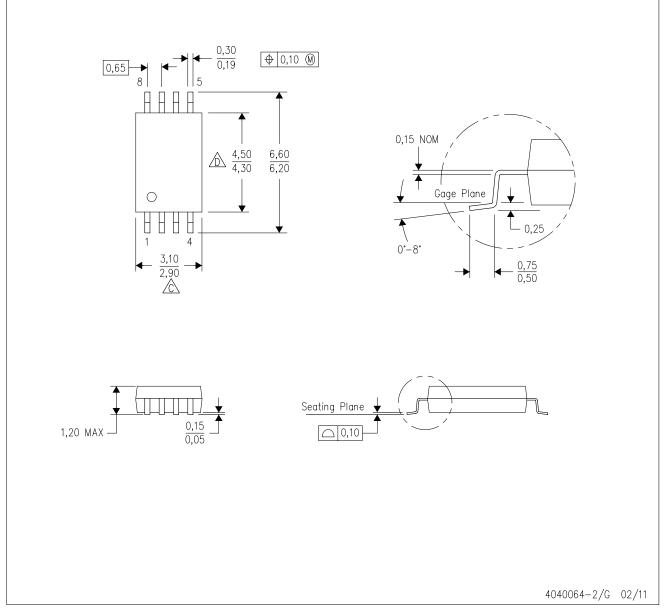
NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Tape and Reel information for the Format Lead Option package.

PW (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



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